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(54) Title: ABRASIVE COMPOSITIONS FOR CHEMICAL MECHANICAL POLISHING AND METHODS FOR USING SAME

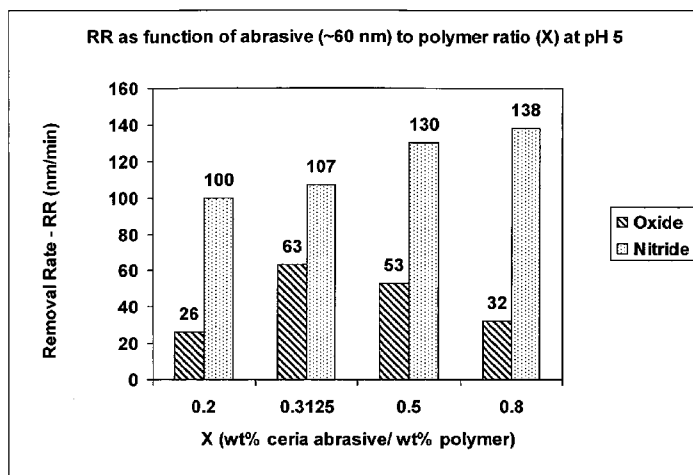


Figure 6

Polish rates of blanket silicon dioxide and silicon nitride films with 0.25% ceria (60 nm) slurry as a function of polymer: abrasive ratio (X) at pH 5

(57) Abstract: A colloidal dispersion for chemical mechanical polishing. The colloidal dispersion is capable of polishing a substrate comprising silicon nitride and silicon oxide with a reverse selectivity ratio of at least about 27, typically at least 50 the reverse selectivity ratio being the ratio of the rate of removal of the silicon nitride to the rate of removal of the silicon oxide.



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